

HALOGEN FREE



# N-Channel 40-V (D-S) MOSFET

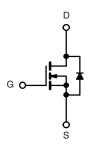
PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A) <sup>a</sup>	Q <sub>g</sub> (Typ.)	
40	0.0088 at V <sub>GS</sub> = 10 V	50	16 nC	
40	0.0105 at V <sub>GS</sub> = 4.5 V	50	10110	

#### **FEATURES**

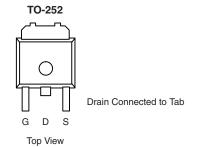
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % UIS Tested
- 100 % R<sub>q</sub> Tested
- PWM Optimized
- Compliant to RoHS Directive 2002/95/EC



- LCD Display Backlight Inverters
- DC/DC Converters



N-Channel MOSFET



Ordering Information: SUD50N04-8m8P-4GE3 (Lead (Pb)-free and Halogen-free)

Parameter	Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	40	
Gate-Source Voltage		V <sub>GS</sub>	± 20	V
	T <sub>C</sub> = 25 °C		50 <sup>a</sup>	
Continuous Drain Current (T <sub>.I</sub> = 150 °C)	T <sub>C</sub> = 70 °C	I_	44	
Continuous Diain Current (1) = 150 °C)	T <sub>A</sub> = 25 °C	I <sub>D</sub>	14 <sup>b</sup>	
	T <sub>A</sub> = 70 °C		11.2 <sup>b</sup>	] A
Pulsed Drain Current		I <sub>DM</sub>	100	7
Continuous Source-Drain Diode Current	T <sub>C</sub> = 25 °C	I.	40	
Continuous Source-Diam blode Current	T <sub>A</sub> = 25 °C	I <sub>S</sub>	2.6 <sup>b</sup>	
Single Pulse Avalanche Current L = 0.1 mH		I <sub>AS</sub>	30	
Avalanche Energy	L = 0.111111	E <sub>AS</sub>	45	mJ
	T <sub>C</sub> = 25 °C		48.1	
Maximum Power Dissipation	T <sub>C</sub> = 70 °C	ь	30.8	$\Box$ w
	T <sub>A</sub> = 25 °C	P <sub>D</sub>	3.1 <sup>b</sup>	l vv
	T <sub>A</sub> = 70 °C		2.0 <sup>b</sup>	
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C

THERMAL RESISTANCE RATINGS					
Parameter		Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>b</sup>	Steady State	R <sub>thJA</sub>	32	40	°C/W
Maximum Junction-to-Case	Steady State	R <sub>thJC</sub>	2.1	2.6	C/ <b>V V</b>

#### Notes:

- a. Package limited.
- b. Surface mounted on 1" x 1" FR4 board.

Document Number: 68647 S10-0109-Rev. B, 18-Jan-10

# SUD50N04-8m8P

# Vishay Siliconix



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static					L	L	
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_{D} = 250 \mu\text{A}$	40			V	
V <sub>DS</sub> Temperature Coefficient	$\Delta V_{DS}/T_{J}$	1. 404		44		mV/°C	
V <sub>GS(th)</sub> Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	I <sub>D</sub> = 1.0 mA		- 5.9			
Gate-Source Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	1.5		3.0	V	
Gate-Source Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zava Cata Valtana Duain Commant		V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V			1		
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = 40 V, V <sub>GS</sub> = 0 V, T <sub>J</sub> = 70 °C			20	μΑ	
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	50			Α	
Dunin Course On Otata Basistanasi		V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		0.0069	0.0088	Ω	
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 4.5 V, I <sub>D</sub> = 15 A		0.0084	0.0105		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 15 A		75		S	
Dynamic <sup>b</sup>							
Input Capacitance	C <sub>iss</sub>			2400		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		260			
Reverse Transfer Capacitance	C <sub>rss</sub>			100			
Total Cata Charres	$Q_g$	V <sub>DS</sub> = 20 V, V <sub>GS</sub> = 10 V, I <sub>D</sub> = 20 A		37	56	nC	
Total Gate Charge				16	24		
Gate-Source Charge	$Q_{gs}$	$V_{DS} = 20 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 20 \text{ A}$		6.5			
Gate-Drain Charge	Q <sub>gd</sub>			4.5			
Gate Resistance	$R_{g}$	f = 1 MHz	2.5	5.5	8.5	Ω	
Turn-On Delay Time	t <sub>d(on)</sub>			30	45		
Rise Time t <sub>i</sub>		$V_{DD} = 20 \text{ V}, R_L = 1 \Omega$		15	25		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 20 \text{ A}, V_{GEN} = 4.5 \text{ V}, R_g = 1 \Omega$		45	70	ns	
Fall Time	t <sub>f</sub>			15	25		
Turn-On Delay Time	t <sub>d(on)</sub>			9	15		
Rise Time	t <sub>r</sub>	$V_{DD} = 20 \text{ V}, R_L = 1 \Omega$		5	10		
Turn-Off Delay Time	t <sub>d(off)</sub>	$I_D \cong 20 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		40	60		
Fall Time	t <sub>f</sub>			5	10		
<b>Drain-Source Body Diode Characteris</b>	tics						
Continuous Source-Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C			40	Α	
Pulse Diode Forward Current <sup>a</sup>	I <sub>SM</sub>				100	A	
Body Diode Voltage	$V_{SD}$	I <sub>S</sub> = 10 A		0.81	1.2	V	
Body Diode Reverse Recovery Time	t <sub>rr</sub>			22	35	ns	
Body Diode Reverse Recovery Charge	Q <sub>rr</sub>	L = 20 A dl/dt = 100 A/vs T = 05 °C		14	25	nC	
Reverse Recovery Fall Time t <sub>a</sub>		$I_F = 20 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		11		no	
Reverse Recovery Rise Time	t <sub>b</sub>			11		ns	

#### Notes:

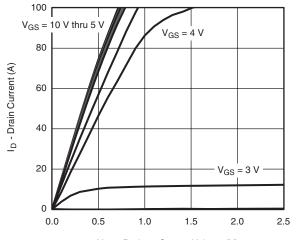
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width  $\leq$  300  $\mu$ s, duty cycle  $\leq$  2 %.

b. Guaranteed by design, not subject to production testing.

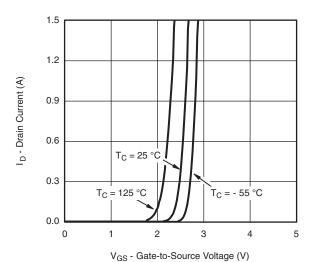


#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

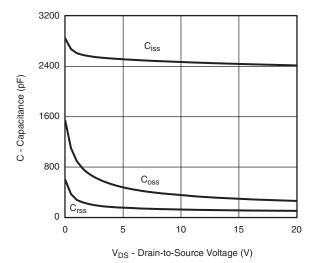


V<sub>DS</sub> - Drain-to-Source Voltage (V)

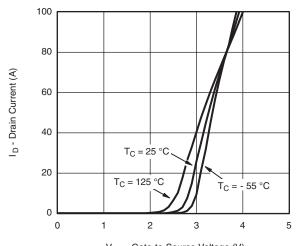
#### **Output Characteristics**



**Transfer Characteristics** 

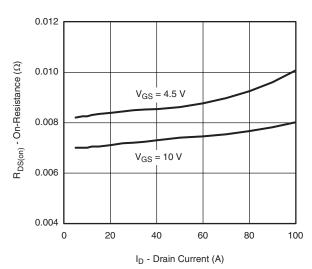


Capacitance

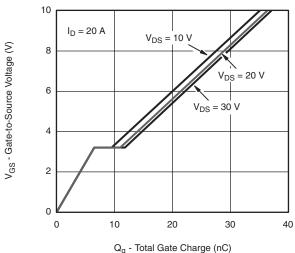


V<sub>GS</sub> - Gate-to-Source Voltage (V)

#### Transfer Characteristics



**On-Resistance vs. Drain Current** 



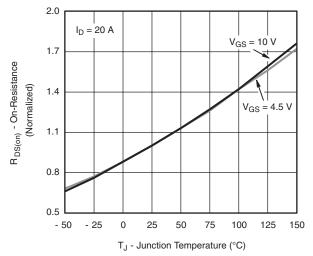
Oata Ohawaa

Gate Charge

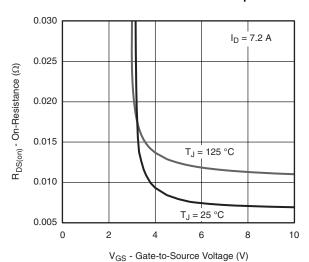
# Vishay Siliconix

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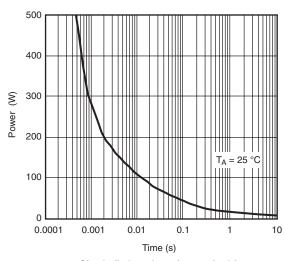
#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



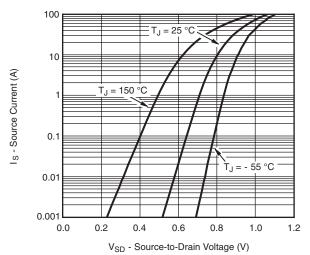
#### On-Resistance vs. Junction Temperature



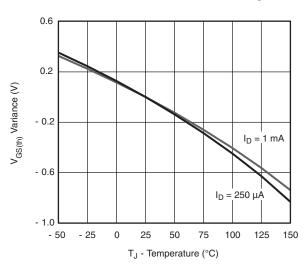
On-Resistance vs. Gate-to-Source Voltage



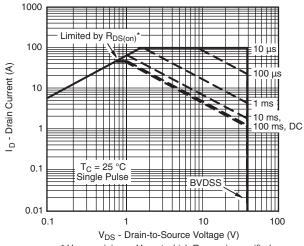
Single Pulse, Junction-to-Ambient



Source-Drain Diode Forward Voltage



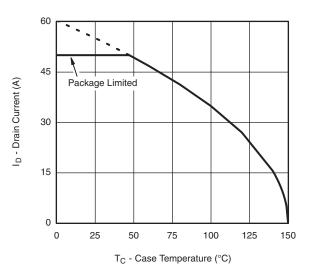
Threshold Voltage



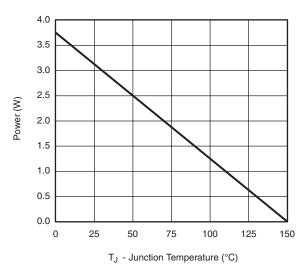
\* V<sub>GS</sub> > minimum V<sub>GS</sub> at which R<sub>DS(on)</sub> is specified **Safe Operating Area, Junction-to-Case** 

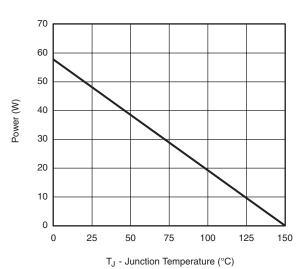


#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



Current Derating\*, Junction-to-Case





Power Derating, Junction-to-Ambient

Power Derating, Junction-to-Case

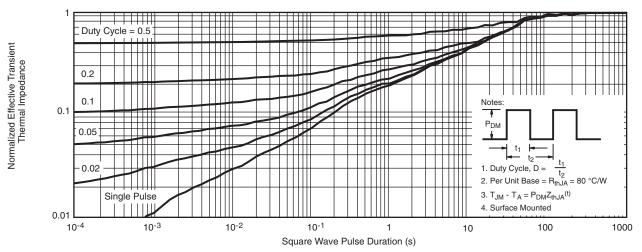
Document Number: 68647 S10-0109-Rev. B, 18-Jan-10

<sup>\*</sup> The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

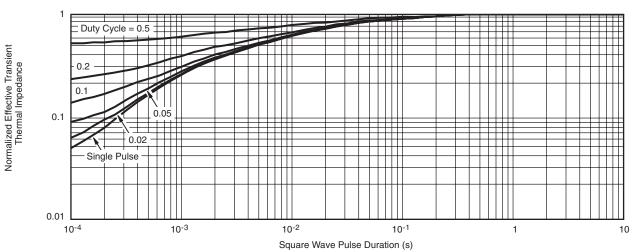
# Vishay Siliconix



#### TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted



#### Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package/tape drawings, part marking, and reliability data, see <a href="https://www.vishay.com/ppg?68647">www.vishay.com/ppg?68647</a>.



## **TO-252AA Case Outline**

#### **VERSION 1: FACILITY CODE = Y**







	MILLIMETERS		
DIM.	MIN.	MAX.	
А	2.18	2.38	
A1	-	0.127	
b	0.64	0.88	
b2	0.76	1.14	
b3	4.95	5.46	
С	0.46	0.61	
C2	0.46	0.89	
D	5.97	6.22	
D1	4.10	-	
Е	6.35	6.73	
E1	4.32	=	
Н	9.40	10.41	
е	2.28 BSC		
e1	4.56 BSC		
L	1.40	1.78	
L3	0.89	1.27	
L4	-	1.02	
L5	1.01	1.52	

#### Note

• Dimension L3 is for reference only



#### **VERSION 2: FACILITY CODE = N**



	MILLIMETERS		
DIM.	MIN.	MAX.	
А	2.18	2.39	
A1	-	0.13	
b	0.65	0.89	
b1	0.64	0.79	
b2	0.76	1.13	
b3	4.95	5.46	
С	0.46	0.61	
c1	0.41	0.56	
c2	0.46	0.60	
D	5.97	6.22	
D1	5.21	-	
Е	6.35	6.73	
E1	4.32 -		
е	2.29 BSC		
Н	9.94	10.34	

	MILLIMETERS		
DIM.	MIN.	MAX.	
L	1.50	1.78	
L1	2.74	ref.	
L2	0.51	BSC	
L3	0.89	1.27	
L4	-	1.02	
L5	1.14	1.49	
L6	0.65	0.85	
θ	0°	10°	
θ1	0°	15°	
θ2	25°	35°	

#### Notes

- Dimensioning and tolerance confirm to ASME Y14.5M-1994
- All dimensions are in millimeters. Angles are in degrees
- Heat sink side flash is max. 0.8 mm
- Radius on terminal is optional

ECN: E22-0399-Rev. R, 03-Oct-2022

DWG: 5347



#### **RECOMMENDED MINIMUM PADS FOR DPAK (TO-252)**



Recommended Minimum Pads Dimensions in Inches/(mm)

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